

Material Declaration Report



Package Type:	LBGA 100L
Pericom Package Code:	NJ100(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	350.760
Termination Plating:	SnAgCu
JESD 97 Pb-free Category:	e1
Plating Thickness (um):	N/A
Tin Whisker Mitigation:	N/A

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	5/29/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
ENCAPSULATION	168.480	ASE	Silica	60676-86-0	90.000	151.6320
			Epoxy resin	Trade Secret	5.500	9.2664
			Phenol resin	Trade Secret	4.500	7.5816
SUBSTRATE	92.100		Copper	7440-50-8	24.910	22.9421
			AUS 308	Proprietary	11.700	10.7757
			Nickel plating	7440-02-0	0.900	0.8289
			Gold plating	7440-57-5	0.090	0.0829
			BT material (GPHL830NX)	Not applicable	35.700	32.8797
			BT material (CCL-HL832NX)	Not applicable	26.700	24.5907
SILICON DIE	4.110		Silicon (Si)	7440-21-3	99.192	4.0768
			Non-hazardous Metal	Proprietary	0.808	0.0332
DIE ATTACH EPOXY	0.600		Silver	7440-22-4	80.000	0.4800
			Di-ester Resin	Proprietary	10.000	0.0600
			Functionalized ester	Proprietary	6.000	0.0360
			Polymeric Resin	Proprietary	2.000	0.0120
			Epoxy Resin	Proprietary	2.000	0.0120
GOLD WIRE	2.470		Gold(Au)	7440-57-5	99.990	2.4698
			Impurities	-	0.010	0.0002
SOLDER BALL	83.000		Tin(Sn)	7440-31-5	96.500	80.0950
			Silver(Ag)	7440-22-4	3.000	2.4900
			Copper(Cu)	7440-50-8	0.500	0.4150

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Substrate	<2	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Ball	<95	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.